

Specification of Automotive MLCC (Reference sheet)



● Supplier : Samsung Electro-Mechanics ● Samsung P/N : CL10B474KO84PNC

● AEC-Q200 Qualified

A. Dimension

Dimension



Size	0603 inch		
L	1.60±0.10 mm		
W	0.80±0.10 mm		
Т	0.80±0.10 mm		
BW	0.30±0.20 mm		

B. Samsung Part Number

<u>CL</u>	<u>10</u>	<u>B</u>	<u>474</u>	<u>K</u>	<u>0</u>	<u>8</u>	<u>4</u>	<u>P</u>	<u>N</u>	<u>C</u>
1	2	3	4	(5)	6	⑦	8	9	10	11

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.60±0.10 mm	W :0.80±0.10 mm
3 Dielectric	X7R	8 Inner electrode	Ni
④ Capacitance	470 nF	Termination	Metal-Epoxy
⑤ Capacitance	± 10%	Plating	Sn 100% (Pb Free)
tolerance		Product	Automotive
Rated Voltage	16 V	Special code	Normal
7 Thickness	0.80±0.10 mm	① Packaging	Cardboard Type, 7" Reel

C. Reliability Test and Judgement condition

Performance	Test condition		
Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature		
Capacitance Change Within ±10 %	Measurement at 24±2hrs after test conclusion		
Tan δ :0.075 max.			
IR :More than 10,000 ™ or 500 ™× μF	Initial Measurement 2*		
Whichever is smaller	Final Measurement 3*		
Appearance : No abnormal exterior appearance	1,000Cycles		
Capacitance Change Within ±10 %	Initial Measurement 2*		
Tan δ :0.075 max.	Final Measurement 3*		
IR : More than 10,000 ^{MΩ} or 500 ^{MΩ} ×μF	Measurement at 24±2hrs after test conclusion		
Whichever is smaller	1 cycle condition : -55+0/-3 °C (30±3min) → Room Temp. (1min)		
	→ 125+3/-0°C (30±3min) → Room Temp. (1min)		
No Defects or abnormalities	Per EIA 469		
Appearance : No abnormal exterior appearance	1,000hrs 85℃/85%RH, Rated Voltage and 1.3~1.5V,		
Capacitance Change Within ±12.5 %	Add 100kohm resistor		
Tan δ :0.075 max.	Initial Measurement 2*		
IR :More than 500 ™ or 25 ™ × µF	Final Measurement 4*		
Whichever is smaller	Measurement at 24±2hrs after test conclusion		
	The charge/discharge current is less than 50mA.		
Appearance : No abnormal exterior appearance	1,000hrs @ 125℃, 200% Rated Voltage,		
Capacitance Change Within ±12.5 %	Initial Measurement 2*		
Tan δ :0.075 max.	Final Measurement 4*		
IR :More than 1,000 № or 50 №× <i>µ</i> F	Measurement at 24±2hrs after test conclusion		
Whichever is smaller	The charge/discharge current is less than 50mA.		
	Capacitance Change Within ±10 % Tan ō:0.075 max. R:More than 10,000 № or 500 №× μF Whichever is smaller Appearance: No abnormal exterior appearance Capacitance Change Within ±10 % Tan ō:0.075 max. R: More than 10,000 № or 500 №× μF Whichever is smaller No Defects or abnormalities Appearance: No abnormal exterior appearance Capacitance Change Within ±12.5 % Tan ō:0.075 max. R:More than 500 № or 25 №× μF Whichever is smaller Appearance: No abnormal exterior appearance Capacitance Change Within ±12.5 % Tan ō:0.075 max. R:More than 1,000 № or 50 №× μF		

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
Physical Dimension	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change Within ±10 %	3 mutually perpendicular axes of the test specimen (18 shocks)					
	Tan δ, IR : Initial spec.	Peak value Duration Wave Velocity					
		1,500G 0.5ms Half sine 4.7m/sec					
		Initial Measurement 2*					
		Final Measurement 5*					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change Within ±10 %	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side					
	Tan δ, IR : Initial spec.	and 2 secure points at corners of opposite sides. Parts mounted					
		within 2" from any secure point. Test from 10~2,000Hz.					
		Initial Measurement 2*					
		Final Measurement 5*					
Resistance to	Appearance : No abnormal exterior appearance	preheating: 150°C for 60~120 sec.					
Solder Heat	Capacitance Change Within ±10 %	Solder pot : 260±5℃, 10±1sec.					
	Tan δ, IR : Initial spec.	Initial Measurement 2*					
		Final Measurement 3*					
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002 or ISO/DIS10605					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
	Tan δ, IR : Initial spec.	Final Measurement 4*					
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	*A capacitor prior to measuring the capacitance is heat treated at					
Characterization	Tan δ :0.05 max.	150 +0/-10 ℃ for 1hour and maintained in ambient air for 24±2 hours					
	IR(25℃): More than 10,000 № or 500 №× <i>μ</i> F	The Capacitance / D.F. should be measured at 25 ℃,					
	Whichever is smaller	$1 \text{ kHz} \pm 10\%, \qquad 1 \pm 0.2 \text{ Vrms}$					
	IR(125℃) More than 1,000 № or 10 №×μF	I.R. should be measured with a DC voltage not exceeding					
	Whichever is smaller	Rated Voltage @25℃, @125℃ for 60~120 sec.					
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit, 2 mm for 60 seconds 1*					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Terminal	Appearance : No abnormal exterior appearance	10 N, for 60 sec.					
Strength(SMD)	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Beam Load	Destruction value should be exceed 20 N	Beam speed: 0.5±0.05 mm/sec					
Temperature	X7R						
Characteristics	From -55 $^{\circ}$ to 125 $^{\circ}$, Capacitance change shou	lld be within ±15%					

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5°C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10 $^{\circ}\mathrm{C}$ for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- $^{\star}3$: Final measurement : Let sit for 24 \pm 2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

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- ⑤ Power plant control equipment
- 6 Atomic energy-related equipment
- ① Undersea equipment
- 8 Traffic signal equipment
- Data-processing equipment
- @ Electric heating apparatus, burning equipment
- Safety equipment
- @ Any other applications with the same as or similar complexity or reliability to the applications